Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A film comprising (A-1) a polyetherimide resin having repeating units of the following structural formula (1), (A-2) a polyetherimide resin having repeating units of the structural formula (2), (B) a polyarylketone resin having a melting peak temperature of 260 degrees C or higher, and a filler in an amount of from 5 to 50 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), wherein a weight ratio of the resin components, [(A-1)+ (A-2)]/(B)], ranges from 70/30 to 30/70 and a weight ratio, (A-1)/ (A-2), ranges from 70/30 to $\frac{30}{70.30}$;

2. (Original) The film according to claim 1, wherein the amount of the filler ranges from 10 to 45 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), and the weight ratio,[(A-1)+ (A-2)]/(B), ranges from 65/35 to 35/65 and the weight ratio, (A-1)/(A-2),ranges from 65/35 to 35/65.

- 3. (Original) The film according to claim 1, wherein the amount of the filler ranges from 20 to 40 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), and the weight ratio, [(A-1)+ (A-2)]/(B), ranges from 65/35 to 45/55 and the weight ratio,(A-1)/(A-2), ranges from 65/35 to 50/50.
- 4. (Previously Presented) A metal laminate comprising the film according to claim 1 and a metal body laminated on at least one side of said film.
- 5. (Original) The metal laminate according to claim 4, wherein the metal body comprises copper, aluminum, or stainless steel.
- 6. (Previously Presented) A multilayered board comprising at least two copper laminated films, each comprising the film according to claim 1 and a copper foil laminated on one side of said film.
- 7. (Original) A resin composition comprising (A-1) a polyetherimide resin having repeating units of the structural formula (1), (A-2) a polyetherimide resin having repeating units of the structural formula (2), (B) a polyarylketone resin having a melting peak temperature of 260 degrees C or higher, and a filler in an amount of from 5 to 50 parts by weight, based on total 100 parts by weight of (A-1), (A-2) and (B), wherein a weight ratio of the resin components, [(A-1)+ (A-2)]/(B), ranges from 70/30 to 30/70 and a weight ratio, (A-1)/(A-2), ranges from 70/30 to 30/70.
- 8. (Previously Presented) A metal laminate comprising the film according to claim 2 and a metal body laminated on at least one side of said film.
- 9. (Previously Presented) A metal laminate comprising the film according to claim 3 and a metal body laminated on at least one side of said film.

- 10. (Previously Presented) A multilayered board comprising at least two copper laminated films, each comprising the film according to claim 2 and a copper foil laminated on one side of said film.
- 11. (Previously Presented) A multilayered board comprising at least two copper laminated films, each comprising the film according to claim 3 and a copper foil laminated on one side of said film.
- 12. (New) The multilayered board according to claim 6, wherein at least two copper laminated films have been heat bonded at a temperature of 260 degrees C or lower.